

(+) 18816996168 eneral Processing Conditions Ponciplastics.com

ESD C 2800 B-55A Black Thermoplastic Polyolefin Elastomer (TEO) **Electrically Conductive ESD Protection** 

## PROPERTIES & AVERAGE VALUES OF INJECTION MOLDED SPECIMENS

ASTM
TEST
D 792
D 955
D 412
D 412
D 412
D 624
D 0040
D 2240
D 257
D 257
ΓM11.11
_

## PROPERTY NOTES

Data herein is typical and not to be construed as specifications.

Unless otherwise specified, all data listed is for natural or black colored materials. Pigments can affect properties.

## GENERAL PROCESSING FOR INJECTION MOLDING

	Eligiisii	31 WELLIC	
Injection Pressure	12000 - 18000 psi	83 - 124 MPa	
Melt Temperature	360 - 410 °F	182 - 210 °C	
Mold Temperature	60 - 150 °F	16 - 66 °C	
Drying	2 hrs @ 175 °F	2 hrs @ 79 °C	
Moisture Content	0.03 %	0.03 %	
Dew Point	0 °F	-18 °C	
PROCESSING NOTES			

English

CI Motrio

23 Apr 2008 SAC

This information is intended to be used only as a guideline for designers and processors of modified thermoplastics. Because design and processing is complex, a set solution will not solve all problems. Observation on a "trial and error" basis may be required to achieve desired results.

Data are obtained from specimens molded under carefully controlled conditions from representative samples of the compound described herein. Properties may be materially affected by molding techniques applied and by the size and shape of the item molded. No assurance can be implied that all molded articles will have the same properties as those

No information supplied by RTP Company constitutes a warranty regarding product performance or use. Any information regarding performance or use is only offered as suggestion for investigation for use, based upon RTP Company or other customer experience. RTP Company makes no warranties, expressed or implied, concerning the suitability or fitness of any of its products for any particular purpose. It is the responsibility of the customer to determine that the product is safe, lawful and technically suitable for the intended use. The disclosure of information herein is not a license to operate under, or a recommendation to infringe any patents.